



Laser Additive Manufacturing of Metallic Materials

Guest Editors:

Prof. Dr. Chunlei Qiu

School of Materials Science and Engineering, Beihang University, Beijing 100191, China

Prof. Dr. Chang-Hwan Choi

Department of Mechanical Engineering, Stevens Institute of Technology, Hoboken, NJ 07030, USA

Deadline for manuscript submissions:
closed (10 October 2023)

Message from the Guest Editors

This Special Issue seeks research papers and review articles that focus on novel development of metallic additive manufacturing. The scope covers all relevant topics, including (but not limited to) laser/electron beam–material interaction; melt flow behavior; process modelling; porosity formation mechanism; cracking mechanism; novel metallurgical phenomena; new microstructural and mechanical property development; defect and microstructural control; stress development and control; novel metallic material development; new structural design and fabrication; and new applications.

Keywords

- Metallic additive manufacturing
- 3D printing
- Microstructural control
- New materials development





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Message from the Editor-in-Chief

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Micromachines Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

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